

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

-20V, -700mA, $R_{DS(ON)} = 400m\Omega @ V_{GS} = -4.5V$

Improved dv/dt capability

Fast switching

Green Device Available

Suit for -1.8V Gate Drive Applications

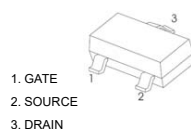
Applications

Notebook

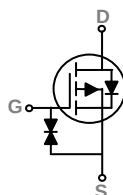
Load Switch

Battery Protection

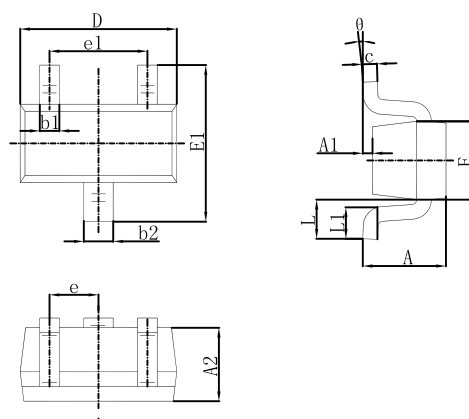
Hand-held Instruments



1. GATE
2. SOURCE
3. DRAIN



SOT-523



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Dimensions in inches and (millimeters)

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 8	V
I_D	Drain Current – Continuous ($T_C=25^\circ\text{C}$)	-700	mA
	Drain Current – Continuous ($T_C=100^\circ\text{C}$)	-250	mA
I_{DM}	Drain Current – Pulsed ¹	-2.1	A
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	312	mW
	Power Dissipation – Derate above 25°C	2.5	mW/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	400	$^\circ\text{C/W}$

DMG1013T

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-20	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.01	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-16V, V _{GS} =0V, T _J =125°C	---	---	-10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±8V, V _{DS} =0V	---	---	±20	uA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-0.5A	---	400	560	mΩ
		V _{GS} =-2.5V, I _D =-0.4A	---	550	780	
		V _{GS} =-1.8V, I _D =-0.1A	---	650	950	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-0.3	-0.6	-1.0	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	3	---	mV/°C

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =-10V, V _{GS} =-4.5V, I _D =-0.2A	---	1	---	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	0.28	---	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	0.18	---	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =-10V, V _{GS} =-4.5V, R _G =10Ω I _D =-0.2A	---	8	---	ns
T _r	Rise Time ^{2, 3}		---	5.2	---	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	30	---	
T _f	Fall Time ^{2, 3}		---	18	---	
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, F=1MHz	---	40	---	pF
C _{oss}	Output Capacitance		---	15	---	
C _{rss}	Reverse Transfer Capacitance		---	6.5	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	-0.7	A
I _{SM}	Pulsed Source Current		---	---	-1.4	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-0.2A, T _J =25°C	---	---	-1.2	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

RATING AND CHARACTERISTIC CURVES (DMG1013T)

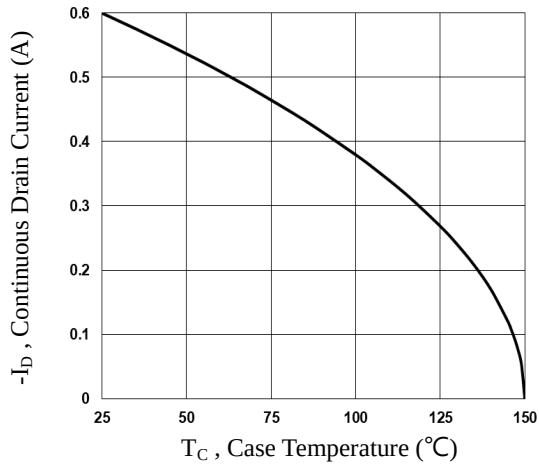


Fig.1 Continuous Drain Current vs. T_C

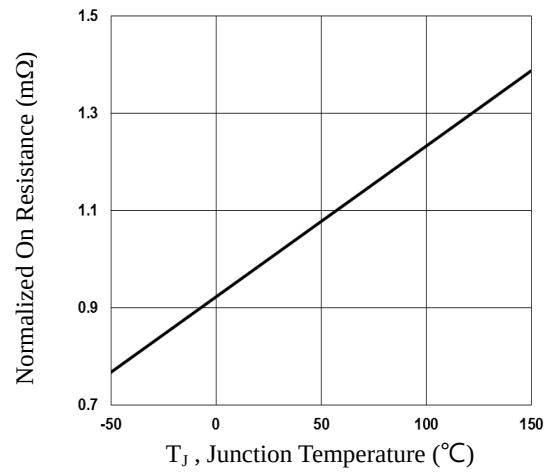


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

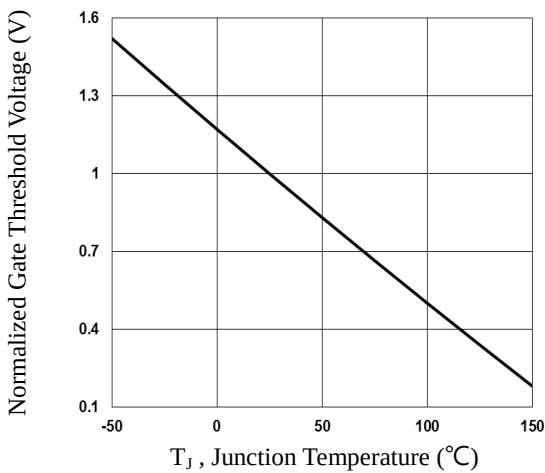


Fig.3 Normalized V_{th} vs. T_J

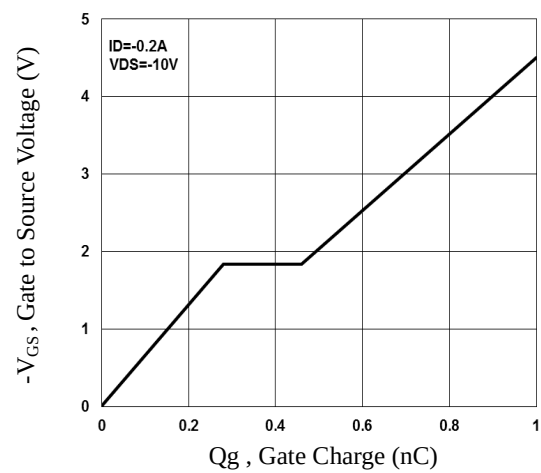


Fig.4 Gate Charge Waveform

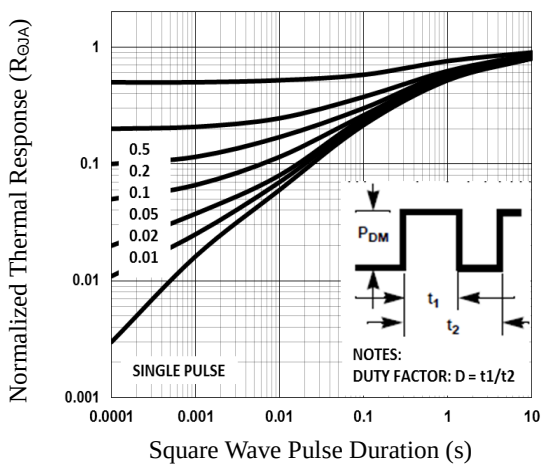


Fig.5 Normalized Transient Response

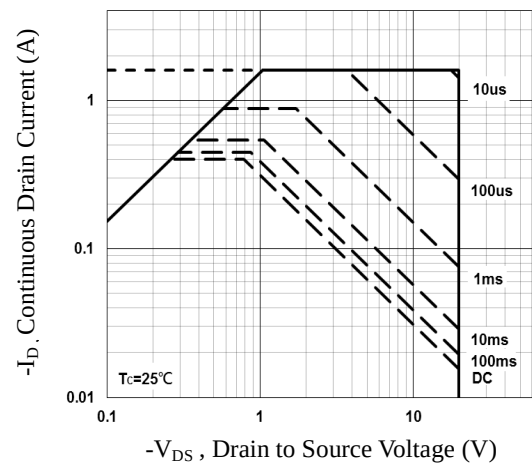


Fig.6 Maximum Safe Operation Area

RATING AND CHARACTERISTIC CURVES (DMG1013T)

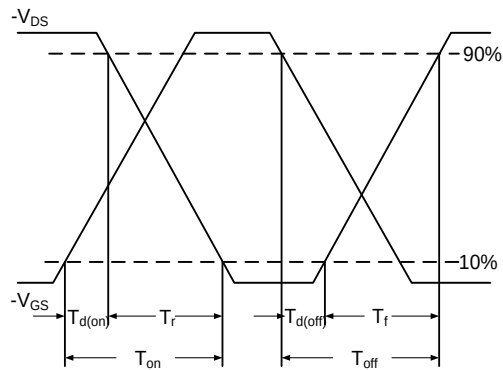


Fig.7 Switching Time Waveform

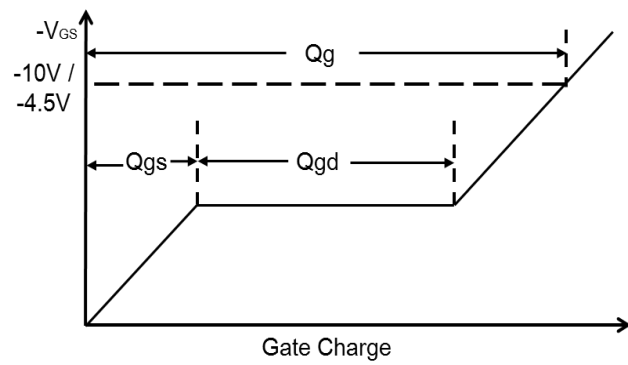


Fig.8 Gate Charge Waveform